



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

HP Pavilion a6700 PC Series

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		2
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Cross screwdriver	
Description #2 Torx Screwdriver	T-15
Description #3 Wire Cutter	Small
Description #4	
Description #5	

3.0 Product Disassembly Process

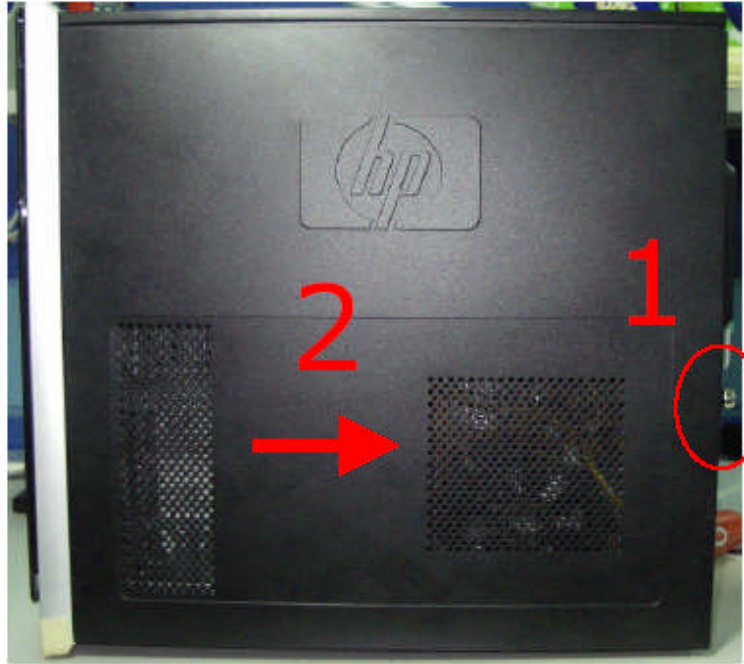
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. unfix thumbscrew 1pcs
2. Remove side cover
3. Release main bezel hook 1,2,3
4. Take out main bezel
5. Unfix 8 screw from MB
6. Remove MB from chassis
7. Unfix 4 screw from chassis
8. Remove PSU from chassis
9. To find the locked screws on external case, there are 6 pcs screws would be screwed out using the screwdriver. And cut off a cable tie using the wire cutter. Shown it on the figure 1 & 2.
10. Pull out an external metal cover, as figure 3.
11. Screwed off 4 pcs screw to remove the main PCBA using the screwdriver. See figure 4.
12. Screwed off 2 pcs screw to remove the small PCBA using the screwdriver. Show on figure 5.
13. To cut out 4 Electrolytic capacitors using the wire cutter. As figure 6.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

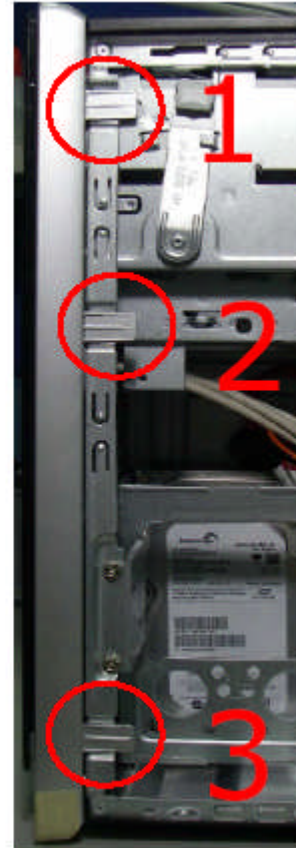
Remove side cover

1. Unfix thumbscrew 1pcs.
2. Remove side cover.



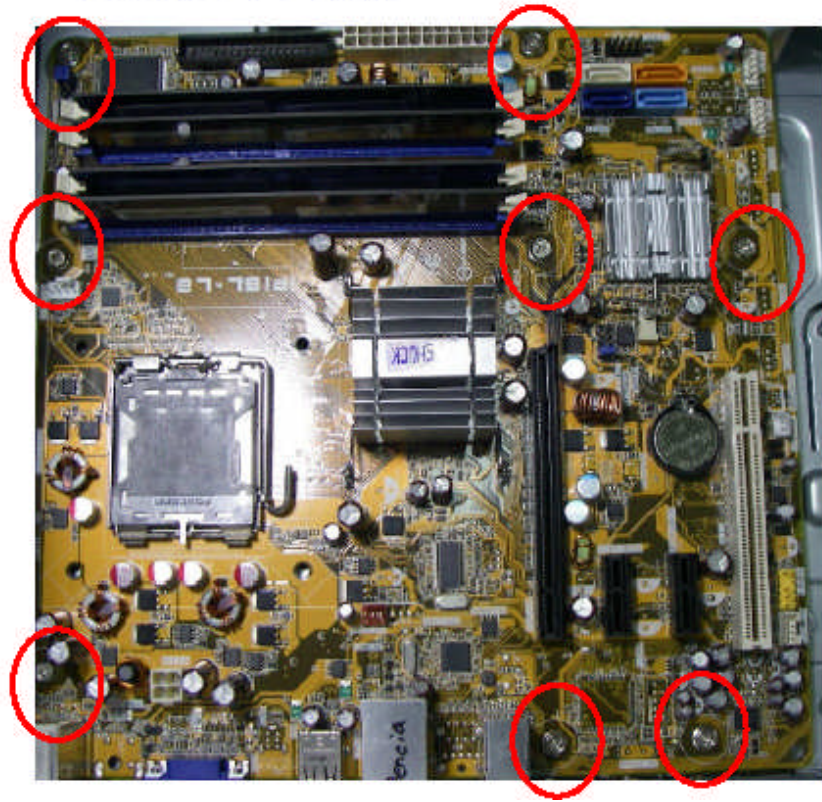
Remove main bezel

1. Release main bezel hook
1, 2, 3.
2. Take out main bezel.

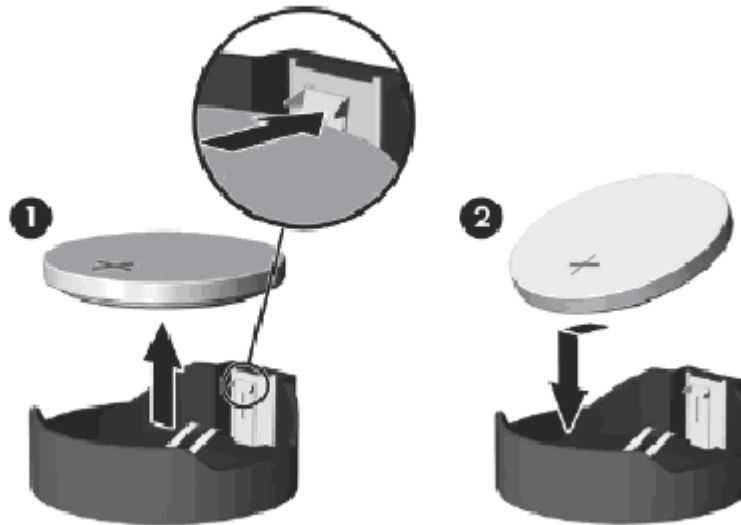


Remove MB

1. Unfix 8 screws from MB.
2. Remove MB from chassis.



Remove coin battery from MB



Remove PSU

1. Unfix 4 screw from chassis.
2. Remove PSU from chassis.

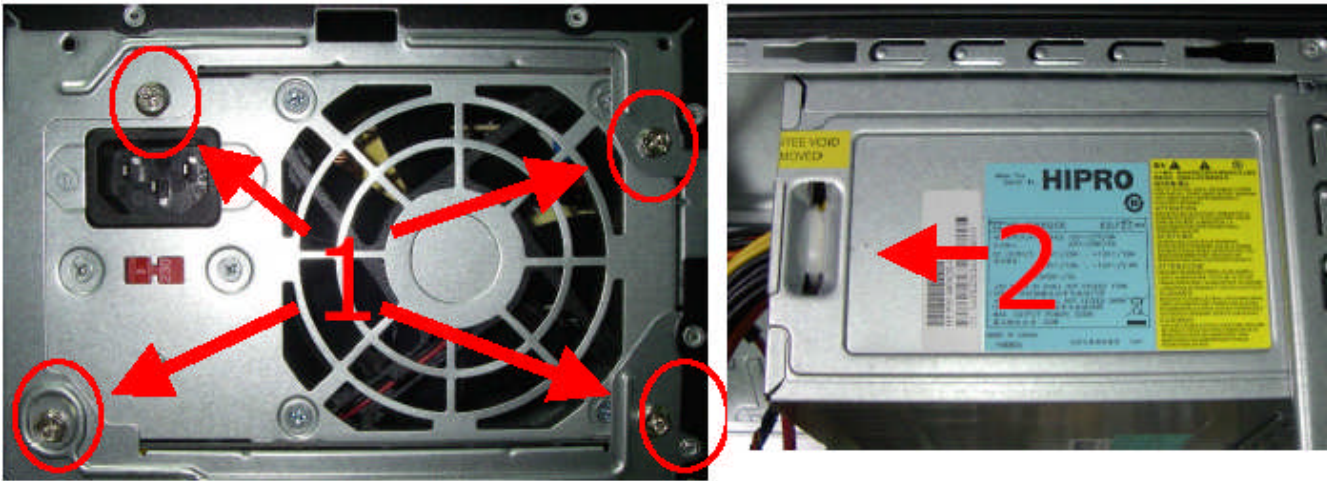


FIGURE 1. Screwed off the screws & cut out the cable tie



FIGURE 2. Screwed off the screws



FIGURE 3. Pull out the metal cover

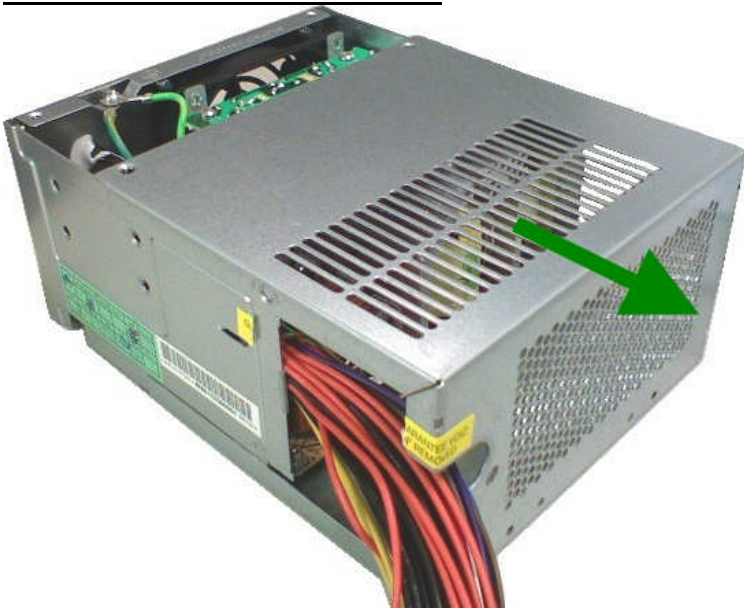


FIGURE 4. Screwed off the screws & remove PCBA

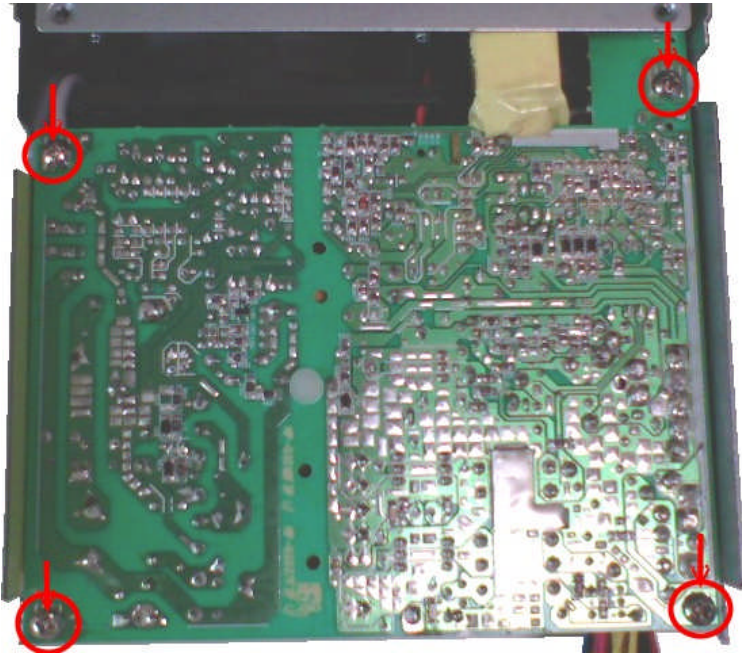


FIGURE 5. Screwed off the screws & remove the small PCBA

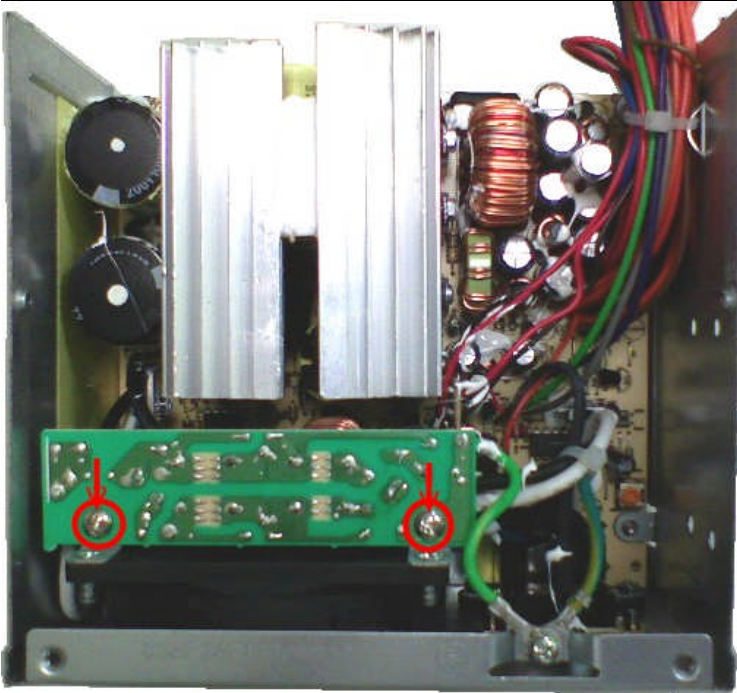
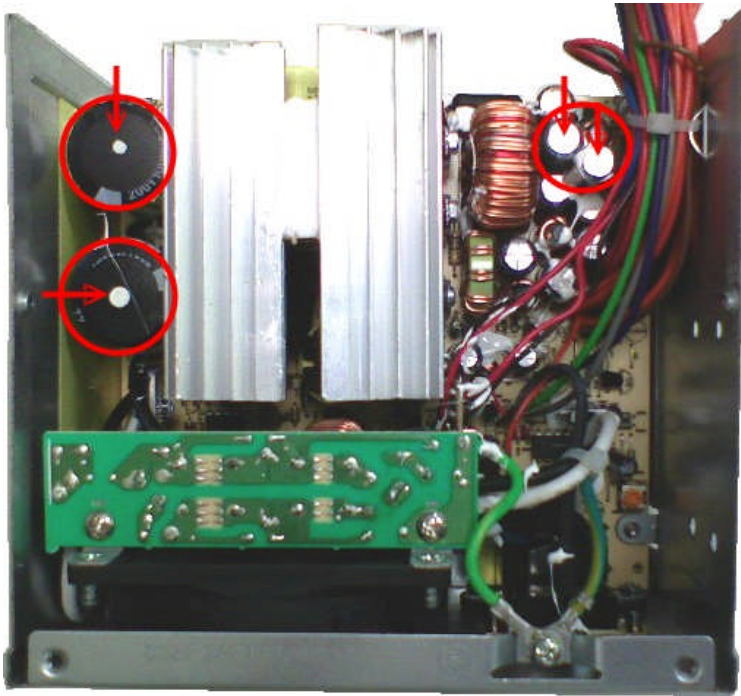
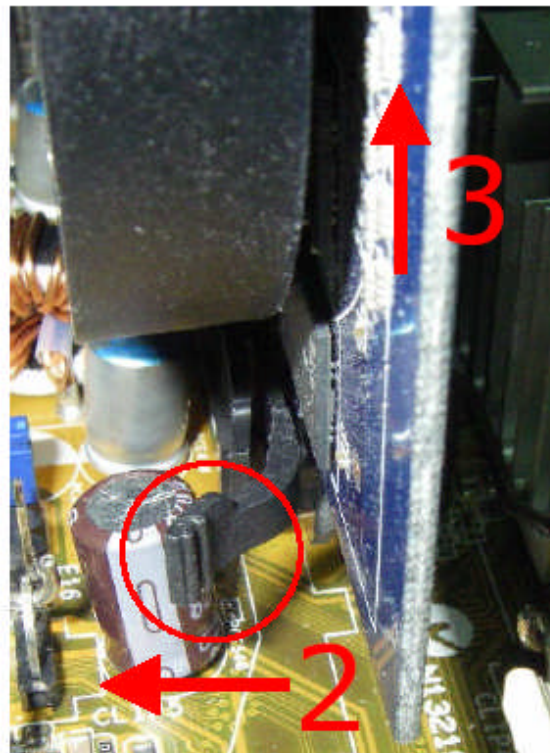


FIGURE 6. Remove the electrolytic capacitors



Remove Add-on card

1. Unfix 1 screw and remove fixed bracket.
2. Press lock.
3. Unplug VGA card.



Remove Heatsink :

1. unfix the screw as arrow point
2. remove H/S from MB

